SLOVENSKI STANDARD
oSIST prEN IEC 61189-2-804:2022

01-januar-2022

Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-804. del: Preskus ugotavljanja razmerja čas-delaminacija - T260, T288, T300

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-804: Test methods for time to delamination - T260, T288, T300

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-804: Méthodes d'essai pour le temps de décollement interlaminaire - T260, T288, T300

Ta slovenski standard je istoveten z: **prEN IEC 61189-2-804:2021**

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards

oSIST prEN IEC 61189-2-804:2022 **en**

91/1761/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

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IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY	
SECRETARIAT: Japan	SECRETARY: Mr Masahide Okamoto
OF INTEREST TO THE FOLLOWING COMMITTEES:	PROPOSED HORIZONTAL STANDARD: ☐ Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: ☐ EMC ☐ ENVIRONMENT ☒ QUALITY ASSURANCE ☐ SAFETY	
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TITLE:

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-804: Test methods for time to delamination - T260, T288, T300

PROPOSED STABILITY DATE: 2027

NOTE FROM TC/SC OFFICERS:

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15 Figure 1 – A typical plot for an epoxy material at an isothermal temperature of 260 °C 6

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17 INTERNATIONAL ELECTROTECHNICAL COMMISSION

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19 **Test methods for electrical materials, printed board and other interconnection**
20 **structures and assemblies -**

21 **Part 2-804: Test methods for time to delamination – T260, T288, T300**

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56 committee TC91

57 The text of this International Standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

58 Full information on the voting for the approval of this International Standard can be found in the report
59 on voting indicated in the above table.

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-804: Test methods for time to delamination – T260, T288, T300

1 Scope

This International Standard specifies a test method to determine the time to delamination of base materials and printed boards using a thermomechanical analyzer (TMA). Temperatures used for this evaluation are typically 260 °C, 288 °C and 300 ºC, but are not limited to these values.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194-1, Printed board design, manufacture and assembly – Vocabulary – Part 1: Common usage in printed board and electronic assembly technologies
IPC-TM-650 No. 2.4.24.1, Time to Delamination (TMA Method)

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194-1 apply.
ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

4 Specimen Preparation

Unless otherwise specified, a minimum of two specimens shall be tested. These specimens shall be taken from random locations of the material to be evaluated.

The edges of each specimen shall be smooth, this may necessitate sanding after etching.

5 Test Specimens

Test specimens shall be unclad laminate material or a printed circuit board. It is acceptable to take specimens from multilayer printed boards with internal conductors present. For determination of a multilayer board's bond integrity, presence of internal conductors is preferred.

All Cu shall be etched from the test specimens using standard industry methods.

The specimen shall be taken at a distance ≥ 25 mm from the edge of the material / circuit board being evaluated. The dimensions of the specimens shall be approximately 6.35mm x 6.35 mm x thickness of the sample.

The specimen needs to lie flat on the test surface, so all edges of the specimen shall be sanded, or equivalent, to make them smooth and free of burrs. Care should be taken that this process does not induce mechanical stresses or heat the specimen.